Features

- High isolation 5000 VRMS
- Supports 0.3 A, 0.6 A, 0.9 A and 1.2 A
- RoHS compliance
- REACH compliance
- External creepage > 7.5mm
- Internal creepage > 6.0mm
- Insulation distance > 0.4mm
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

Description

The random phase power Triac consists of a Triac and a photo-Triac, which is optically coupled to a gallium arsenide Infrared emitting diode, and house in a 7-lead DIP package. It also comes with different lead forming options.

Applications

C 1

A 2

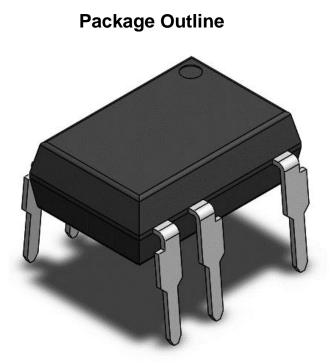
C 3

C|4

- Home appliances
- Industrial equipment

Schematic

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Note: Different bending options available. See package

dimension.

8 MT1

6 MT2

5 G



Absolute Maximum Rating at 25°C

Symbol	Paramete	ers	Ratings	Units	Notes
Viso	Isolation voltage		5000	Vrms	
T _{OPR}	Operating temp	perature	-40 ~+85	°C	
Tstg	Storage tempe	erature	-40 ~+125	°C	
т	Soldering temp	perature	260	°C	
T _{SOL}	Wave soldering te	emperature	260	°C	
Emitter				·	
lF	LED forward of	current	50	mA	
VR	LED reverse v	voltage	6	V	
IFP	Peak forward	current	1	А	
Pin	Power dissipation		75	mW	
Detector					
Vdrm	Repetitive peak OFF-state voltage		600	V	
		CTT0223	0.3		
	Continuous Current Load	CTT1223	0.6	Α	
I _{T(RMS)}		CTT2223	0.9		
		CTT3223	1.2		
		CTT0223	3		
	Peak Current Load	CTT1223	6	— A	
Ітѕм		CTT2223	9		
	CTT3223		12		
Pout	Power dissip	pation	800	mW	
Pτ	Total power dissipation		850	mW	



Electrical Characteristics $T_A = 25^{\circ}C$ (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	-	1.3	V	
I _R	Reverse Current	$V_R = 6V$	-	-	5	μΑ	
CIN	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

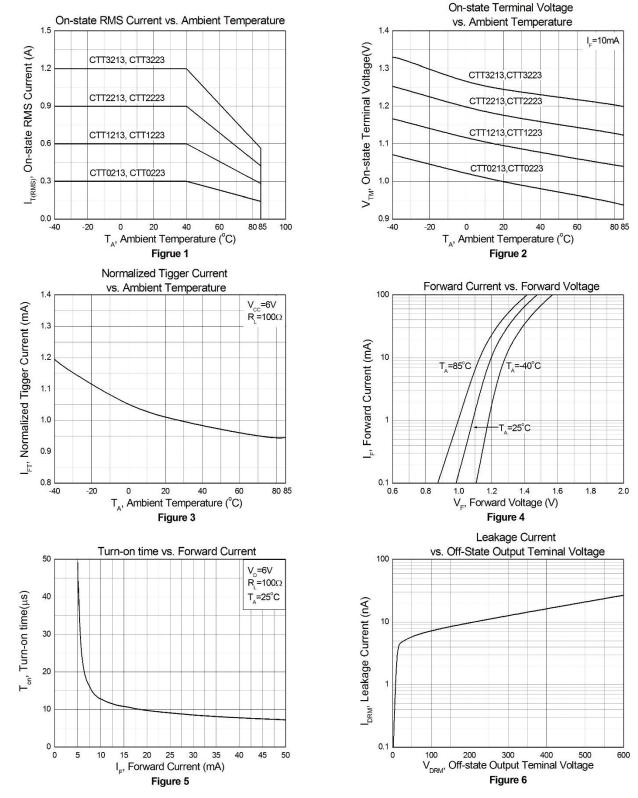
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
Idrm	Peak Blocking Current	IF= 0mA, VDRM= Rated VDRM	-	-	100	uA	
V _{TM}	Peak On-State Voltage	I_{F} = Rated I_{FT} , I_{TM} = 100mA	-	-	2.5	V	
dv/dt	Critical Rate of Rise off-State Voltage	VPEAK= Rated VDRM	200	-	-	V/µs	

Transfer Characteristics

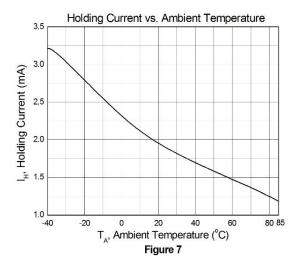
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
IFT	Input Trigger Current	Terminal Voltage = 3V	-	-	10	mA	
Ін	Holding Current		-	-	25	mA	
Rio	Isolation Resistance	VIO= 500VDC	1x10 ¹¹	-	-	Ω	
Сю	Isolation Capacitance	f= 1MHz	-	0.25	-	pF	



Typical Characteristic Curves



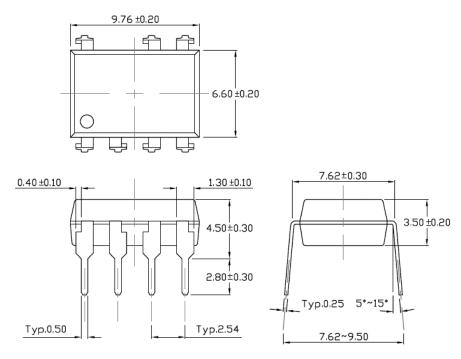




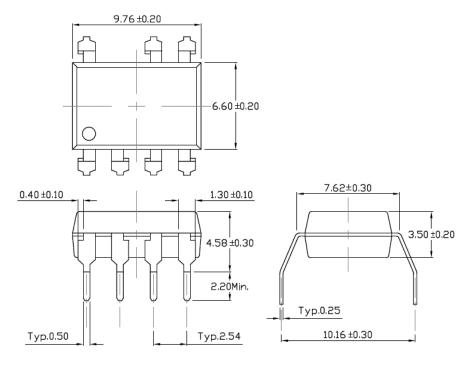


Package Dimension Dimensions in mm unless otherwise stated

Standard DIP – Through Hole

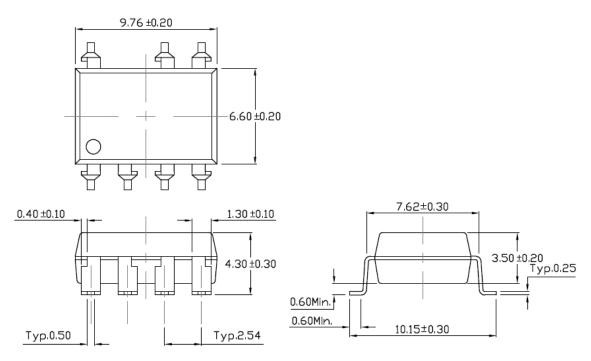


Gullwing (400mil) Lead Forming – Through Hole (M Type)

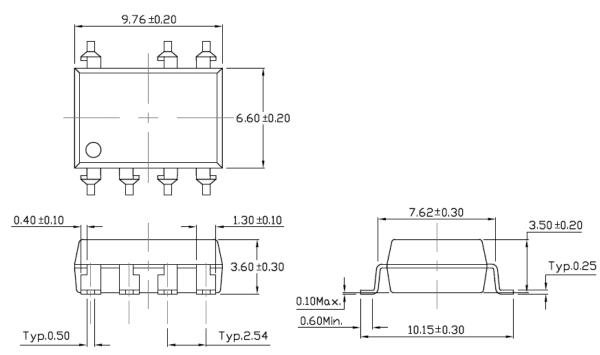




Surface Mount Lead Forming (S Type)

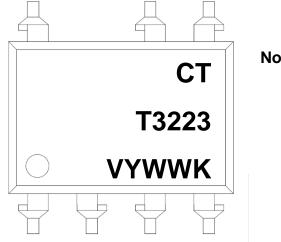


Surface Mount (Low Profile) Lead Forming (SL Type)





Device Marking



ote:	
СТ	: Denotes "CT Micro"
T3223	: Product Number
V	: VDE Safety Mark (option)
Y	: Fiscal Year
WW	: Work Week
K	: Production Code

Ordering Information

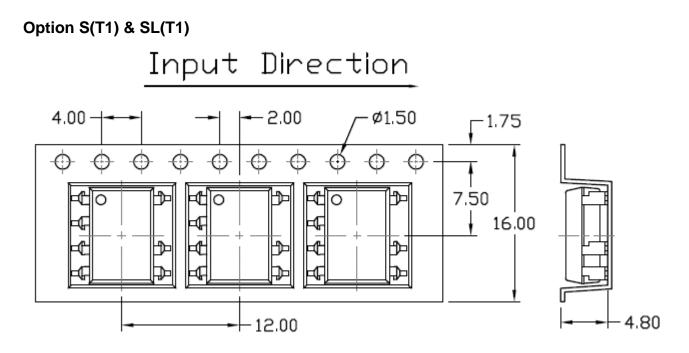
CTTX223(V)(Y)(Z)

СТ	= Denotes "CT Micro"
TX223	= Product Number (Current Rating Option X=0, 1, 2, or 3)
V	= VDE safety mark option (V, or none)
Y	= Lead form option (S, SL, M or none)
Z	= Tape and reel option (T1, T2 or none)

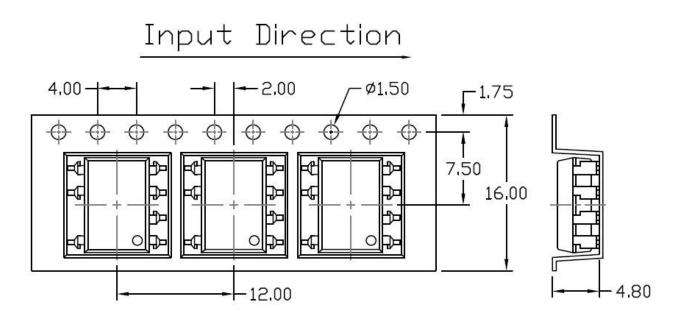
Option	Description	Quantity
None	Standard 8 Pin Dip	40 Units/Tube
М	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping	1000 Units/Reel



Carrier Tape Specifications Dimensions in mm unless otherwise stated



Option S(T2) & SL(T2)





Wave soldering (JEDEC22A111 compliant)

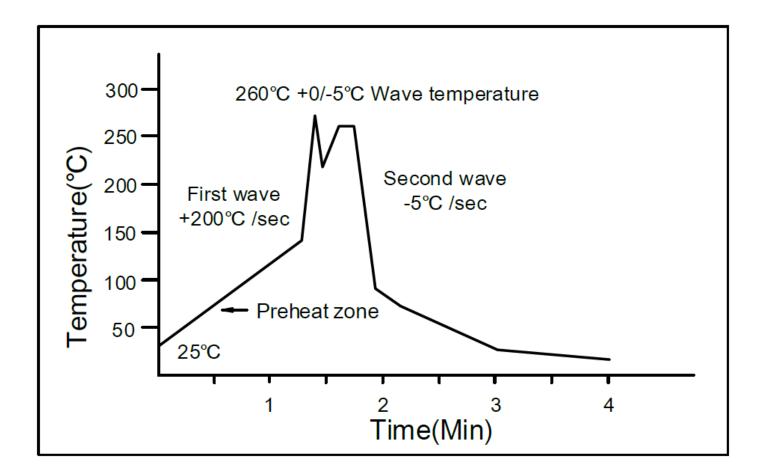
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.

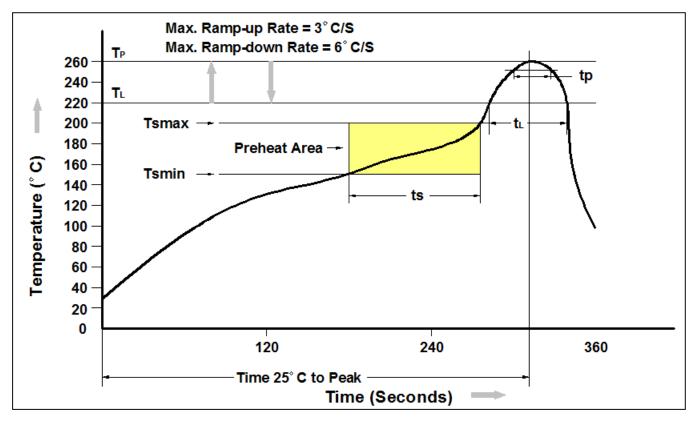


Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended. Temperature: 350+0/-5°C Time: 3 sec max.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile		
Temperature Min. (Tsmin)	150°C		
Temperature Max. (Tsmax)	200°C		
Time (ts) from (Tsmin to Tsmax)	60-120 seconds		
Ramp-up Rate (t∟ to t _P)	3°C/second max.		
Liquidous Temperature (TL)	217°C		
Time (t_L) Maintained Above (T_L)	60 – 150 seconds		
Peak Body Package Temperature	260°C +0°C / -5°C		
Time (t _P) within 5°C of 260°C	30 seconds		
Ramp-down Rate (T_P to T_L)	6°C/second max		
Time 25°C to Peak Temperature	8 minutes max.		



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